

Docket No.: M4065.0222/P222-B  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re Design Application of:  
Tongbi Jiang, et al.

Application No.: (Divisional application of Ser.  
No.09/680,473 under rule 53(b))

Group Art Unit: 3729

Filed: Concurrently herewith

Examiner: Paul D. Kim

For: METHOD OF MAKING A CENTER BOND  
FLIP CHIP SEMICONDUCTOR CARRIER  
(as amended)

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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**PRELIMINARY AMENDMENT**

Dear Sir:

Prior to examination on the merits, please amend the above-identified U.S.  
patent application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims beginning on page 3 of  
this paper.